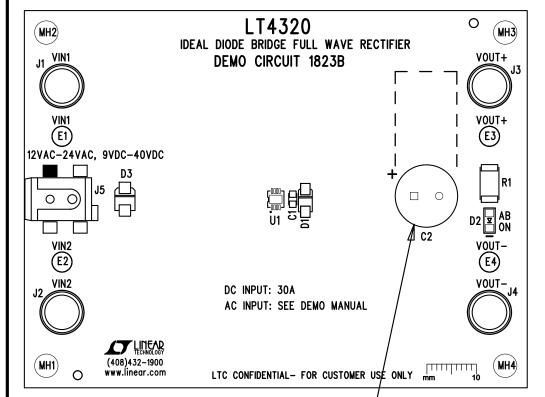
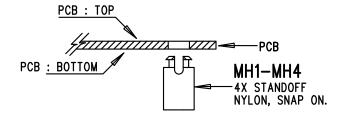
REVISION HISTORY				
EC0	REV	DESCRIPTION	APP. ENG.	DATE
-	1	REBUILD WITH CHANGE	KAUGH H.	10-06-15



## NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- 2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
- 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 4. NO SHUNT.
- 5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
- 7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



8. INSTALL D2 AS SHOWN BELOW:

C2 NEEDS TO BE LAID DOWN ON THE BOARD

